

ABSTRACT

Provides an interposer capable of preventing breaking of wiring pattern with an IC chip loaded on a package substrate. Stress due to a difference in thermal expansion coefficient between a multilayer printed wiring board 10 having a large thermal expansion and the IC chip 110 having a small thermal expansion can be absorbed by locating the interposer 70 between the package substrate 10 and the IC chip 110. Particularly by using an insulation substrate 80 whose Young's modulus is 55 to 440Gpa as the insulation substrate constituting the interposer 70, stress is absorbed within the interposer 70.